

What is claimed is:

1. A semiconductor package comprising:
a substrate including a redundant bond finger, an added bond finger connected to a
5 redundant solder ball pad;
a semiconductor chip having an added bond pad attached to the substrate;
a normal wire bonding unit coupled between the added bond pad and the redundant
bond finger; and
an added wire bonding unit coupled between the redundant bond finger and the added
10 bond finger.

15 2. The semiconductor package of claim 1, further comprising:
an encapsulant for encapsulating the semiconductor chip, the normal and added wire
bonding units.

20 3. The semiconductor package of claim 2, further comprising:
a solder ball connected to the redundant solder ball pad.

4. The semiconductor package of claim 1, wherein the substrate is a single-layer
25 substrate on which a printed circuit pattern is formed.

5. The semiconductor package of claim 1, wherein the substrate is a double-layer
substrate or a multi-layer substrate.

25 6. The semiconductor package of claim 1, wherein a solder mask is not formed
on the added bond finger.

7. The semiconductor package of claim 1, wherein the added wire bonding unit
is formed over the substrate.

30 8. The semiconductor package of claim 1, wherein the added wire bonding unit
is formed on an outer region of the substrate on which the semiconductor chip is mounted.

10 9. The semiconductor package of claim 1, wherein the added wire bonding unit
is one unit or a plurality of units.

15 10. The semiconductor package of claim 1, wherein the semiconductor chip is
attached to the substrate using an adhesive.

11. The semiconductor package of claim 1, wherein the added bond finger is made
by further extending the printed circuit pattern on the substrate.

10 12. The semiconductor package of claim 1, wherein the added bond finger has the
same pad shape as that of the redundant bond finger.

15 13. A semiconductor package comprising:
a substrate including a first printed circuit pattern connected to a redundant bond
finger and a second printed circuit pattern connected to a redundant solder ball pad;
a semiconductor chip attached to the substrate; and
an added wire bonding unit coupled between the first printed circuit pattern to the
second printed circuit pattern.

20 14. The semiconductor package of claim 13, further comprising:
an encapsulant for encapsulating the semiconductor chip and the added wire bonding
unit.

25 15. The semiconductor package of claim 14, further comprising:
a solder ball connected to the redundant solder ball pad.

16. The semiconductor package of claim 13, wherein the first and second printed
circuit patterns each have a width that enables wire bonding to be performed thereon.

30 17. A method for manufacturing a semiconductor package, the method
comprising:

10 forming an added bond finger coupled to a redundant solder ball pad, and a redundant bond finger on a substrate;

15 attaching a semiconductor chip having an added bond pad to the substrate ;

20 forming a normal wire bonding unit coupled between the added bond pad to the redundant bond finger; and

25 forming an added wire bonding unit coupled between the redundant bond finger to the added bond finger.

18. The method of claim 17, further comprising:

10 encapsulating the semiconductor chip, the normal wire bonding unit, and the added wire bonding unit.

15 19. The method of claim 18, further comprising:

20 attaching a solder ball to a solder ball pad including the redundant solder ball pad.

25 20. The method of claim 17, wherein the substrate is a single-layer substrate, a double-layer substrate, or a multi-layer substrate.

21. The method of claim 17, wherein the added wire bonding is performed on an

20 outer region of the substrate on which the semiconductor chip is attached.

25 22. The method of claim 17, wherein a single added wire bonding unit or a

plurality of added wire bonding units are formed during performing the added wire bonding.

23. A method for manufacturing a semiconductor package, the method

comprising:

preparing a substrate including a first printed circuit pattern connected to a redundant bond finger and a second printed circuit pattern connected to a redundant solder ball pad;

attaching a semiconductor chip to the substrate; and

30 forming an added wire bonding unit coupled between the first printed circuit pattern and the second printed circuit pattern.

24. The method of claim 23, further comprising:
encapsulating the semiconductor chip and the added wire bonding unit.

25. The method of claim 24, further comprising:
attaching a solder ball to a solder ball pad including the redundant solder ball pad.